

英特爾邊緣到雲端技術產業論壇

Taiwan Edge to Cloud Conference

Intel Open IP 浸沒式冷卻參考設計

供應鏈的驗證整合與合作分享

Supply Chain Integration, Validation and Collaboration

intel®

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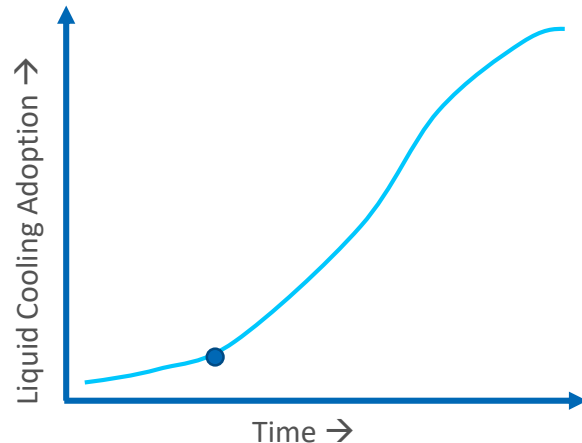
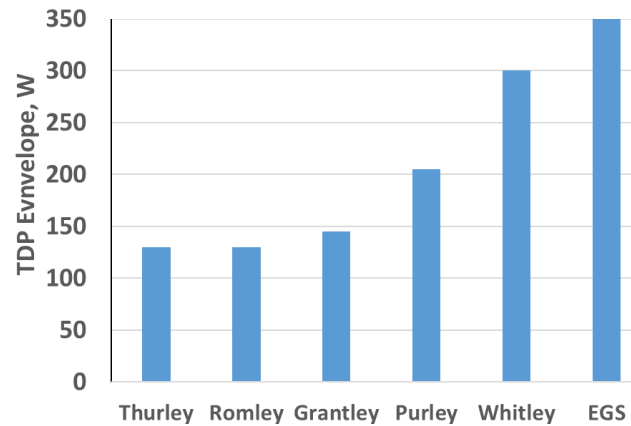
Jun Zhang Intel CESG PE

Agenda

- Liquid Cooling Key Drives & Forecast
- Advanced Cooling Solutions Journey
- Open IP Immersion Cooling Roadmap Update
- 2023 Goal
 - 4U deployment kit update
 - Edge AAIC solutions
 - Synthetic Oils continuous work in progress
 - Innovated immersion cooling server heat sink
 - Optical AOC for immersion cooling update
- Ecosystem Collaboration
- Call to Action

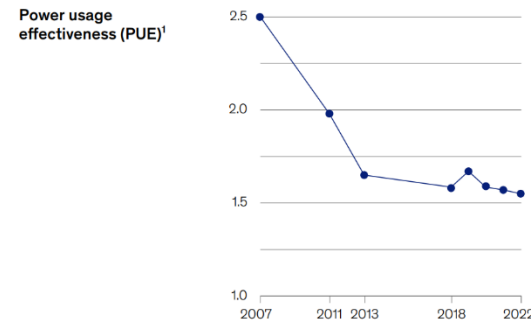
Drivers of Liquid Cooling

Component Power



Sustainability and Regulatory

Gains in power usage efficiency have stalled during the past decade.



¹A measure that shows the amount of power used by the computing equipment in a data center relative to its total energy consumption. The closer PUE is to 1, the more efficient a data center's power usage is.
Source: Uptime Institute Intelligence

McKinsey & Company

Recent Examples of Legislation to Reduce Environmental Impact

| | |
|-----------------|--|
| Amsterdam | <ul style="list-style-type: none"> • PUE* limits on data centers • Moratorium on new licenses until environmental impact assessed – city wants heat re-use |
| Singapore | <ul style="list-style-type: none"> • Restrictions on new builds due to land use, energy |
| Santa Clara, CA | <ul style="list-style-type: none"> • On-site generation must use non-fossil fuels |
| Shanghai | <ul style="list-style-type: none"> • New data centers must have PUE* 1.3 or less |
| European Union | <ul style="list-style-type: none"> • New rules governing server energy use when idle, thermal reporting and recyclability |

* PUE – Power Usage Effectiveness Source: Uptime Institute Intelligence, October 2018

Edge Growth



On-premises Edge

Network Edge or Regional Data Center

- By 2025 - 75% of Data created outside central data centers*
- Pollution, humidity, space constraints at Edge

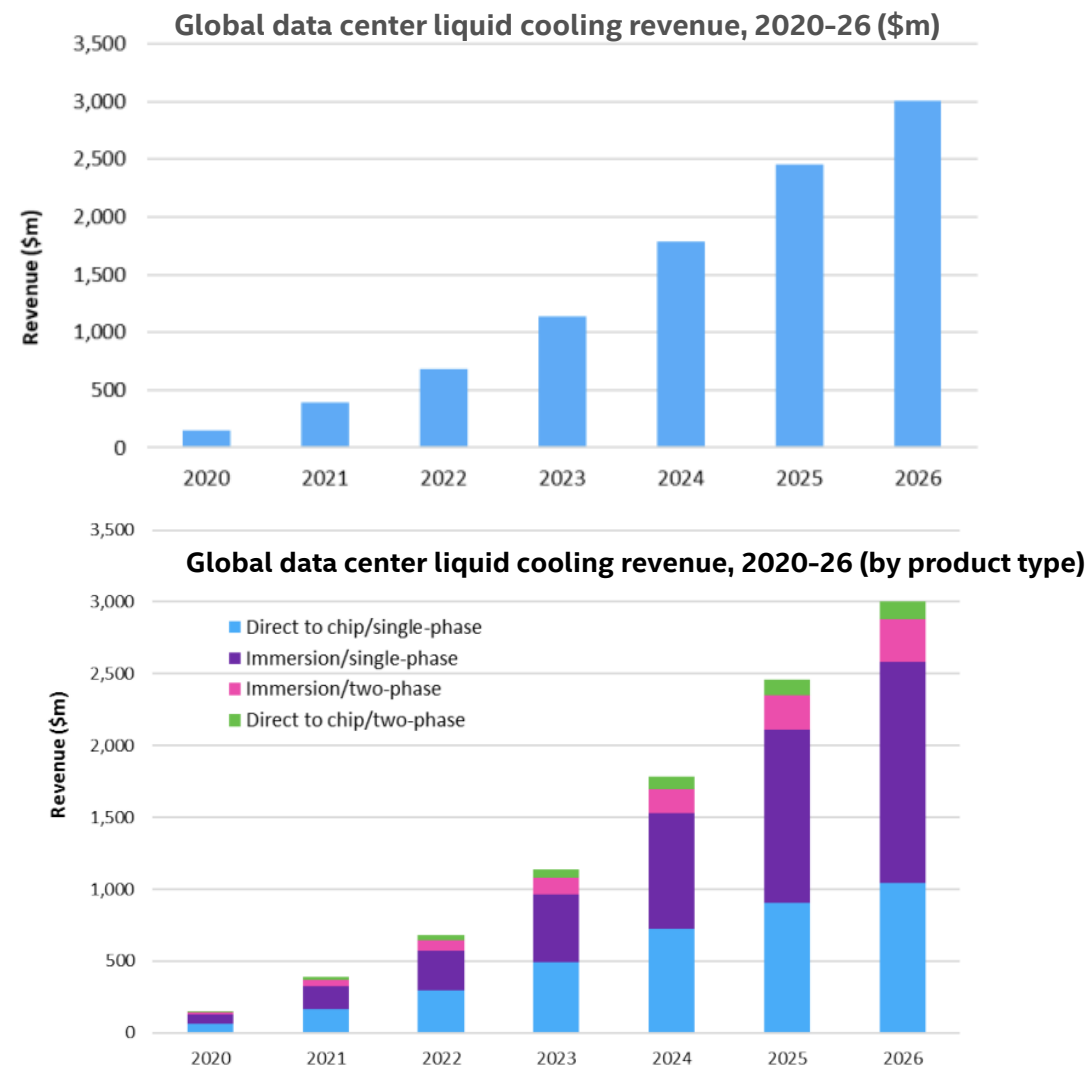
Data Center Liquid Cooling Forecast

- Omdia market forecast data center thermal management market revenue to grow at a 17.5% CAGR from 2021 – 2026, on track to reach \$11.6bn
- Liquid cooling market revenue to top \$3bn (to cool 26% server TAM) by 2026
- By 2026, immersion liquid cooling will represent more than 60% of data center liquid cooling revenue

| | 2020 | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 | CAGR 2021–26 |
|--------------------------------------|-------|-------|--------|--------|--------|--------|--------|--------------|
| Total data center thermal management | 4,390 | 5,187 | 6,096 | 7,152 | 8,481 | 10,008 | 11,611 | 17.50% |
| Liquid cooling | 152 | 391 | 679 | 1,134 | 1,781 | 2,457 | 3,005 | 50.40% |
| Liquid cooling to total ratio | 3.50% | 7.50% | 11.10% | 15.90% | 21.00% | 24.50% | 25.90% | |

Source: Omdia

Source: Omdia Data Center Thermal Management Market Analysis - 2022



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Advanced Cooling Solutions Journey

2018

Purely

- 1) Data center intelligent power management

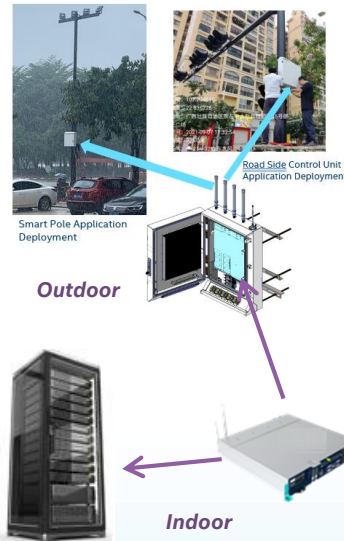


PUE Saving

2019

Purely Refresh

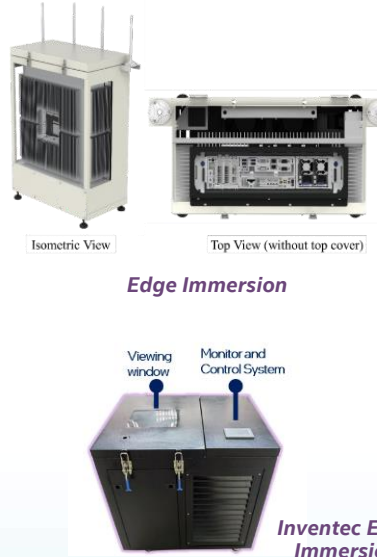
- 1) Cloud edge server
- ✓ Indoor
 - ✓ Outdoor



2020

Whitley

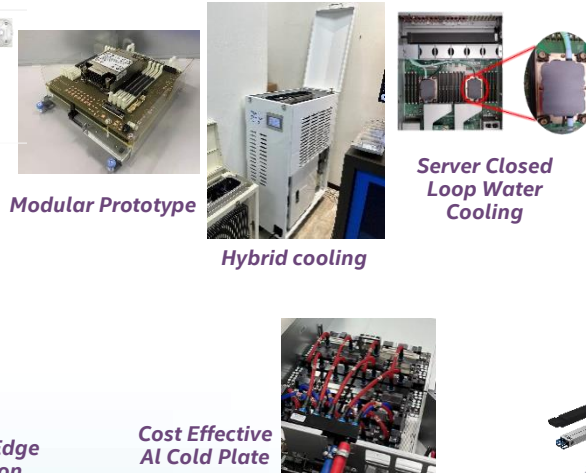
- 1) Cloud edge immersion
- 2) Eagle Stream modular server prototype



2021-2022

Eagle Stream

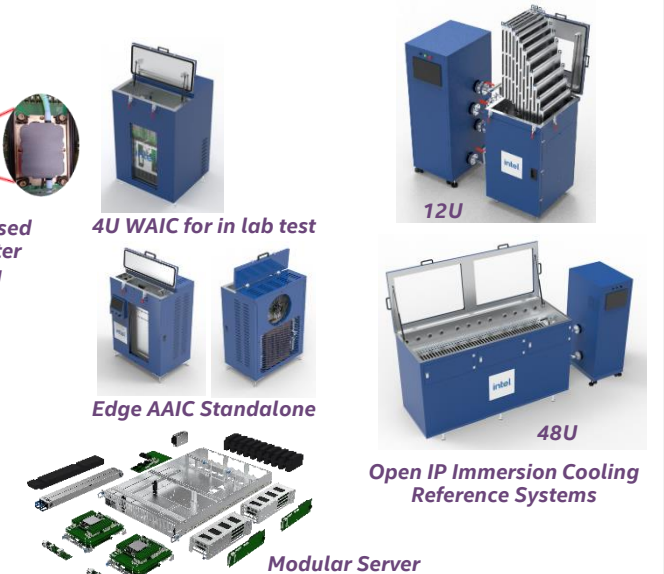
- 1) Cloud edge hybrid cooling POC
- 2) Closed loop water cooling
- 3) Open IP immersion cooling reference solutions



2023 & beyond

Next Gen Intel® Xeon® Platform

- 1) Continue adv cooling tech
- 2) Optimizing modular server arch



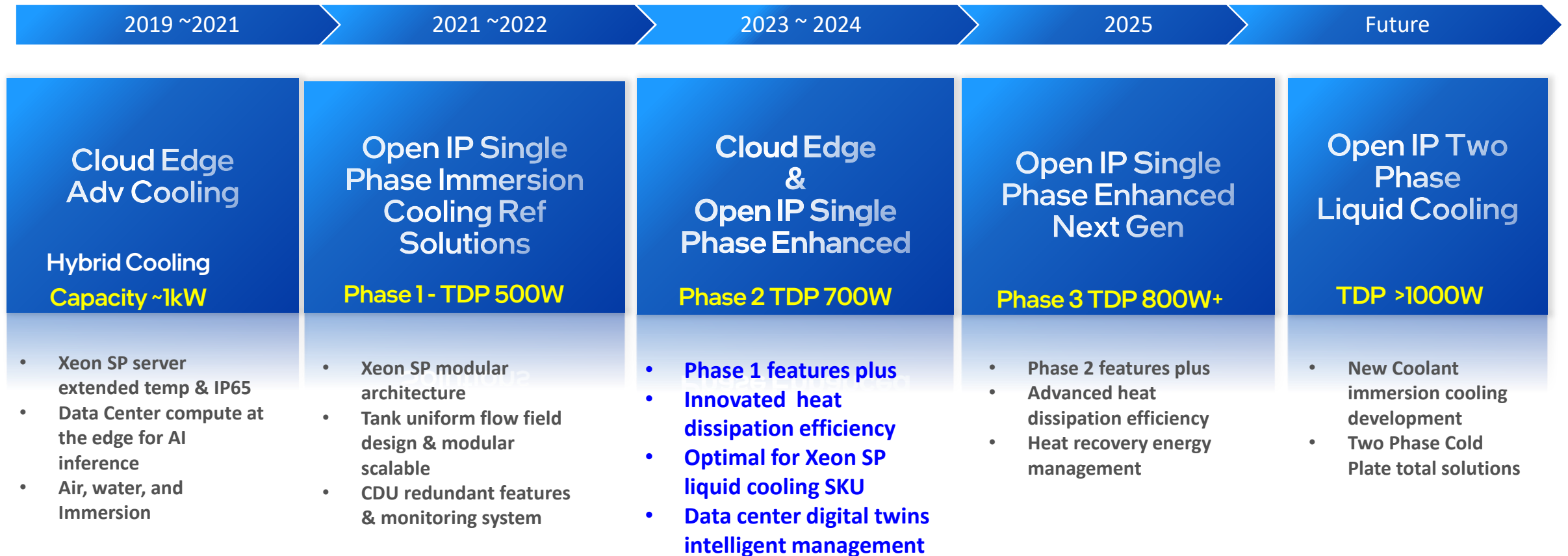
Data Center Compute at the Edge – Storage, Networking, computing, security, AI

Modular Architecture -- regardless server form factor & cost effective

Advanced cooling -- air cooling alternatives

All product plans and roadmaps are subject to change without notice.

Advanced Cooling Roadmap

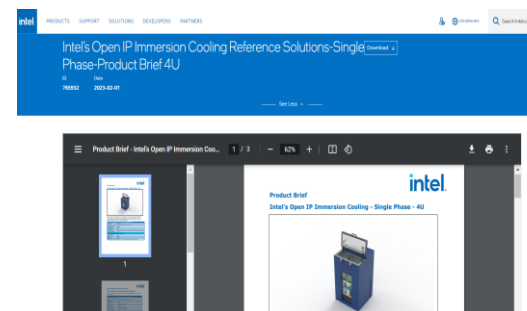


All product plans and roadmaps are subject to change without notice.

Intel Open IP Immersion Cooling Server Deployment Kit



- 4U@10 kW – Water Assisted Immersion Cooling (WAIC)
- In Lab Validation - Server, Coolant, & Material Compatibility
- Single Phase-Product Brief 4U
 - Now on Intel.com, ID: 765932
- User guide on Intel.com soon
 - Installation and operation
 - Validated partner solutions updates
- Current Intel Open IP immersion cooling Collaboration Partner
 - OxM: Foxconn, Inventec, Compal, UfiSpace, Accton (server & switch in tank design, validation & debug...)
 - CSP: OPPO, Softbank, KDDI
 - Coolant: Dow, FastCool, Perstorp, Chevron (coolant reliability, server cable compatibility, grease compatibility...)
 - HSK supplier: Mandala (sample available), Microloops, Forcecon, Auras, Cooler Master (design concept)
 - Optical module AOC: Formerica, JPC (sample available)



Intel Open Ip Immersion Cooling Edge to Data Center

4U@7 kW and 2U@3 kW Air Assisted Immersion Cooling (AAIC)

- Agile for DC Workload Tuning with Immersion Cooled Server and Xeon Based Processors
- For Cloud Edge Immersion Cooling System Ready for Production



4U@7 kW AAIC



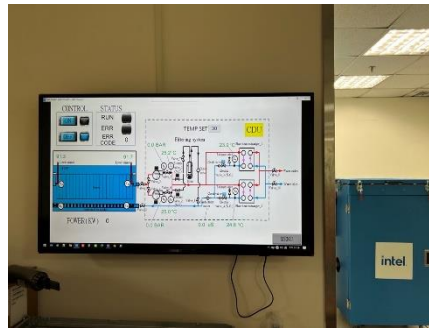
2U@3 kW AAIC

Synthetic Oils Continuous Work in Progress

- Material Compatibility
- Safety Requirements for Data Center Deployment
 - Flash point safety certification by 3rd party lab
 - Integrated IDC safety management
- Synthetic Oil Life Cycle

Continue coolant optimization for real world deployment
with friendly environment & cooling performance

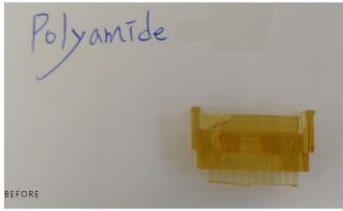
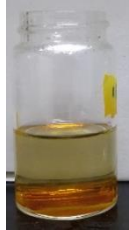
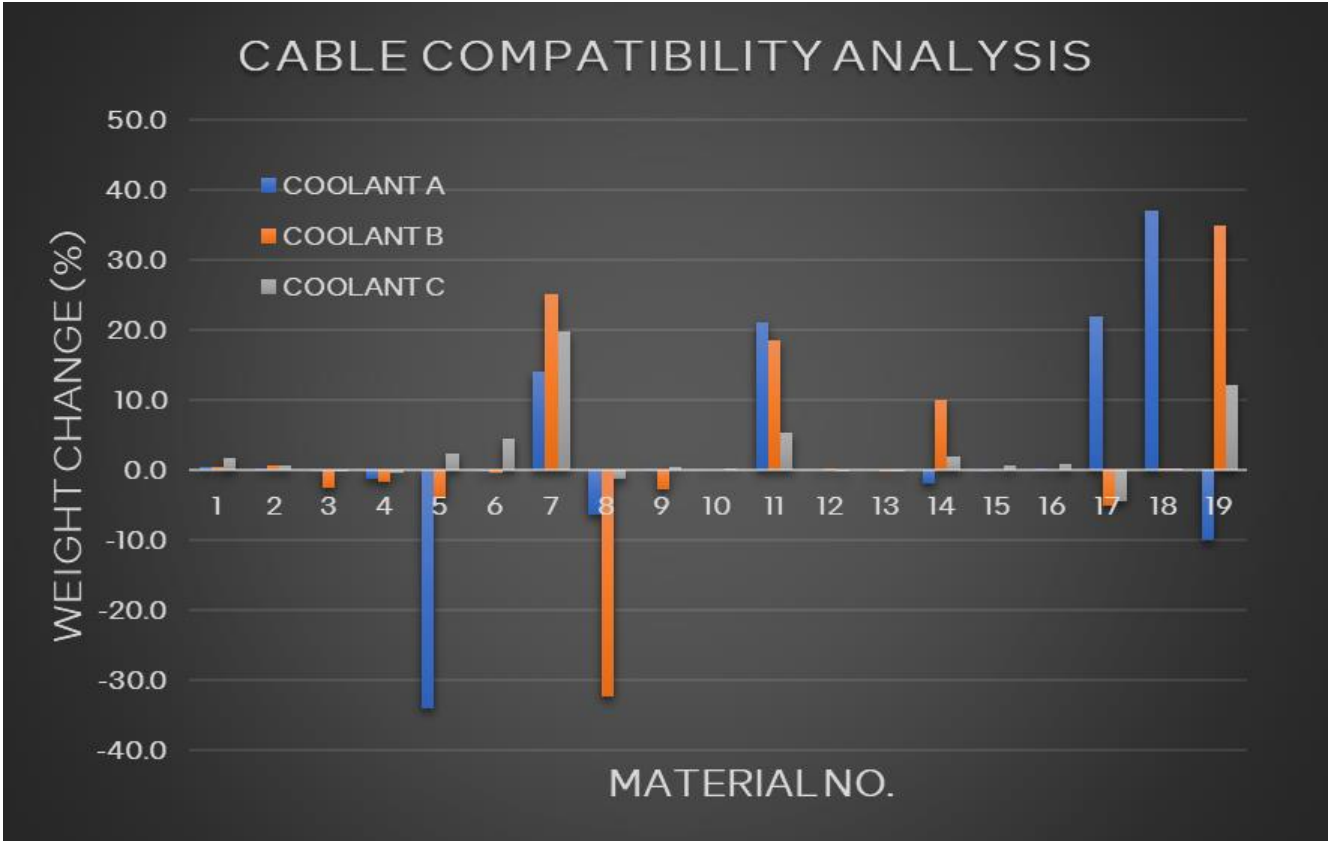
Intel Open IP Test Environment



Evaluating material compatibility in synthetic oils with Intel Open IP immersion cooling system

Key Components for Immersion Cooling: Material Compatibility

| Aging for Coolant A, B, and C | |
|-------------------------------|--|
| No | Cable Material |
| 1 | PBT+LCP+Gold & Tin plated terminal |
| 2 | PA66+Gold plated terminal |
| 3 | PCB FR4 |
| 4 | PA66 |
| 5 | Polyester Fabric & Acrylic Glue |
| 6 | PET |
| 7 | Ethylene-vinyl acetate copolymer + flame retardant |
| 8 | Teflon |
| 9 | Stainless steel |
| 10 | Nickel-plated stainless steel |
| 11 | Polyamide |
| 12 | PBT (halogenated) |
| 13 | PBT (Halogen Free) |
| 14 | PVC |
| 15 | Gold plated terminal |
| 16 | Tin plated terminal |
| 17 | PVC+Cu |
| 18 | FKM |
| 19 | EPDM |

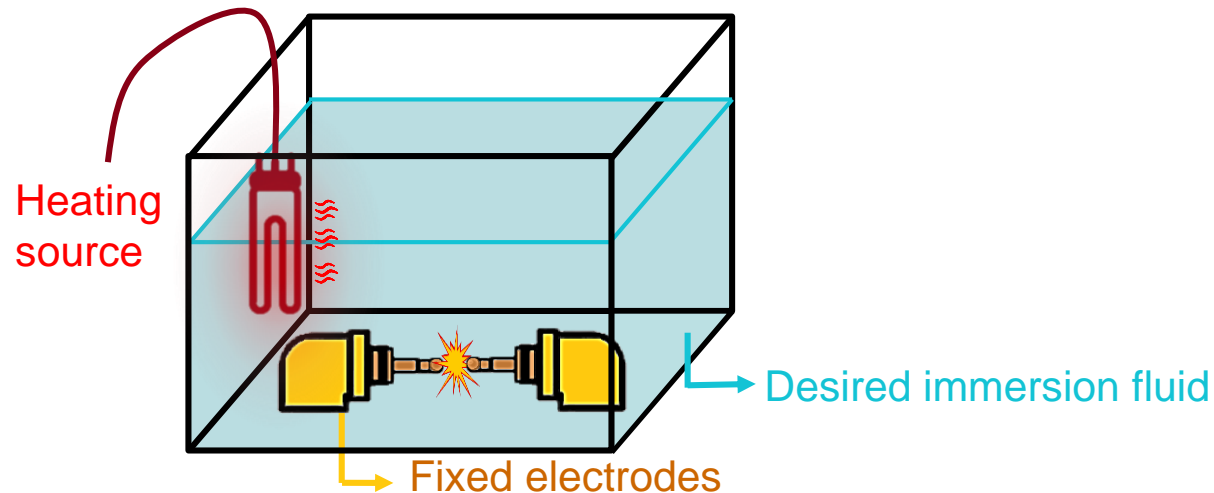


- Cycling tests for coolant composition analysis
- Cable material alternatives or coolant tuning

Coolant Safety & Life Cycle

Safety Verification POC

1. Place controlled heating source that can generate very high temperature instantaneously
2. The electrodes are installed in the test container and a spark is generated by applying a momentary high voltage
3. Repeat the experiment several times to confirm reproducibility and stability



Coolant Working-Life Monitoring

1. Periodic testing of coolant properties is required.
2. Important test item : color, viscosity, dielectric constant, loss tangent, acidity, specific heat capacity, flash point, break down voltage...etc.

Plan for Third-party Verification Service

- Test item : viscosity, acidity, specific heat capacity, flash point (open/closed cup), pour point, thermal conductivity, break down voltage, dielectric constant (1 ~ 10GHz), loss tangent (1 ~ 10GHz), metal composition analysis, thermogravimetric analysis, volume resistance, surface tension.
- Immersion Coolant Compatibility 、 Aging 、 safety

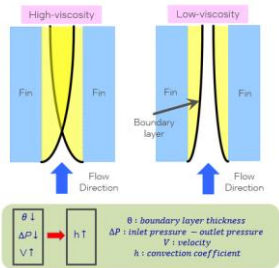
Integrated IDC Safety Management - Demo



Combine Coolant Safety & IDC Management to Meet the Deployment Criteria

Innovated Immersion Cooling Server Heat Sink

Intel HSK Design Concept

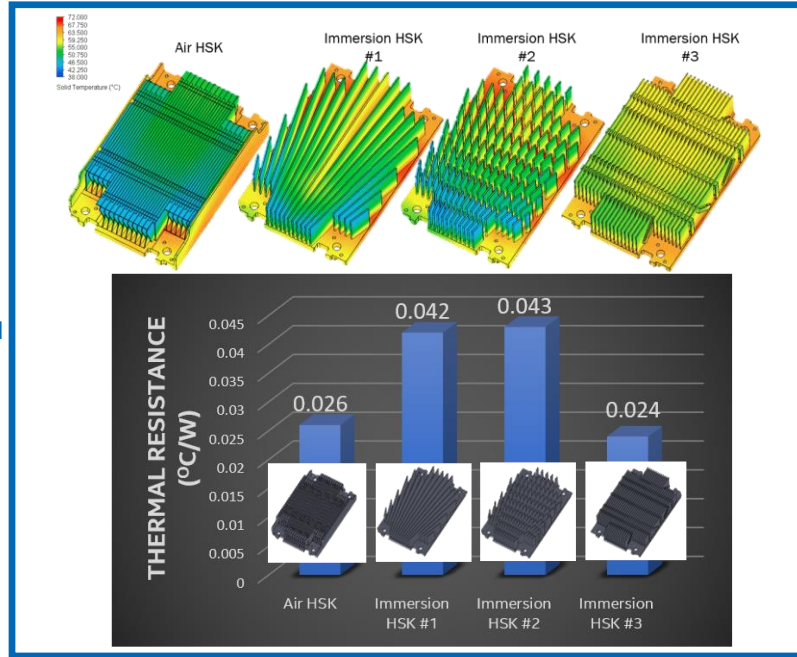


Fluorinated fluid simulation parameters

- Thermal conductivity 0.065 W/mK
- Density 1855 kg/m³
- Absolute viscosity 4.1 centipoise
- Specific heat 1100 J/kgK



Simulation

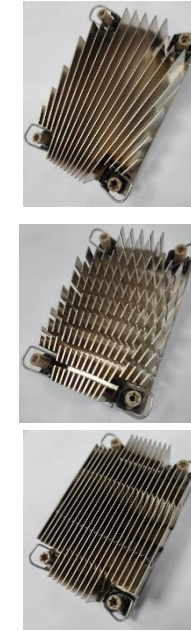


Manufacture

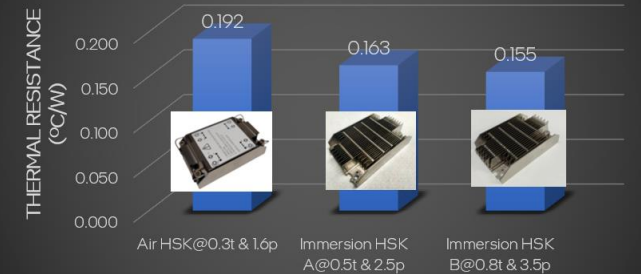


Output

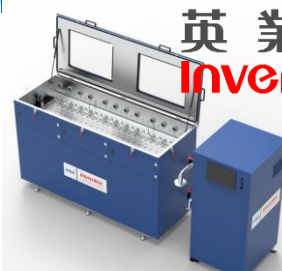
- IEEE, joint white paper
- HSK design guide
- Sample ready for verification
- Calibrate simulation parameters



Single Phase Immersion Cooling HSK Reference Design



Case Study: Synthetic oil, Kinematic Viscosity: 35 mm²/s @ 40 °C



英業達
Inventec

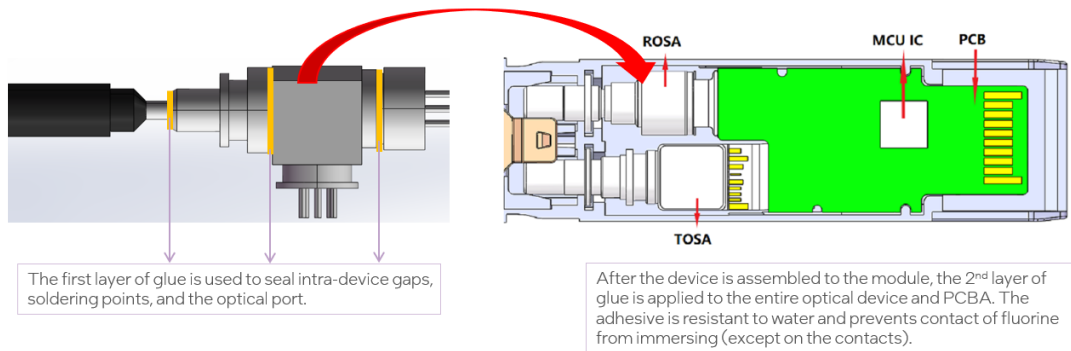


Foxconn
Industrial
Internet

Samples validating now in Intel Open IP immersion cooling system
Continue to bring up more partner solutions

Key Components for Immersion Cooling: Active Optical Cable (AOC) Solution

AOC Transceiver



Sample Available Now



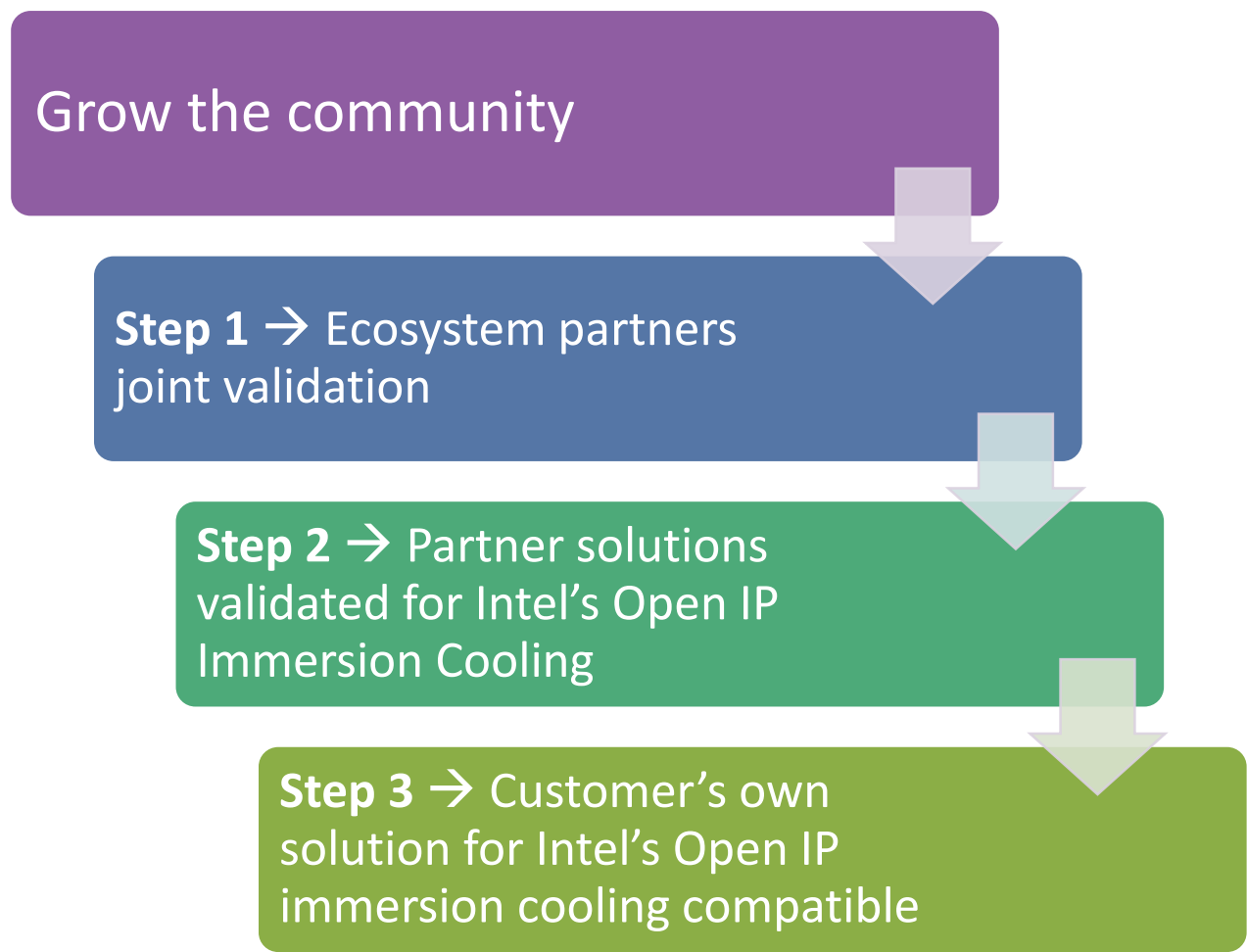
Advantages Sealing Technology

- Complete protection against water and fluorine
- The optical cable is halogen-free and corrosion-resistant
- Supports direct immersion or spraying
- The seal can effectively block cooling liquid from entering the optical circuit, with no adverse affects on the optical circuit



Validating in Intel Open IP immersion cooling system

Ecosystem Collaboration



Intel's Open IP Immersion Cooling Reference Solutions – Single Phase - 4U

User Guide

April 2023

Revision 1.0

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Ecosystem Collaboration

7.1 Community for Intel's Open IP Immersion Cooling

Intel is launching Open IP immersion cooling solutions and reference design, collaborating with ecosystem partners to meet the industry needs and create a three-win situation among Intel, ecosystem partners and the environment.

The community is to activate the entire ecosystem, and to accelerate the real deployment to meet energy saving and carbon reduction. The community welcome the ecosystem partner solutions adopt Intel Open IP immersion cooling reference design for joint validation.

Figure 7.1-1. Intel's Open IP Immersion Cooling Community



7.2 Partner Solutions Validated for Intel's Open IP Immersion Cooling

Intel Open ecosystem to ecosystem partners collaboration for validated & proven partners solutions ready to meet end customer's requirements. The table provides with the information for server and key components that have been verified with Intel Open IP immersion cooling reference systems.

This table will continue to be maintained to expand the cooperation of the ecosystem.

Table 7-2. Server System information

| Server System | | | |
|---------------|--------------|-------------|--------|
| Company | Description | Part Number | Remark |
| Compal | Eagle Stream | SR120-2 | |
| Foxconn | Eagle Stream | D-5222 | |
| Inventec | Eagle Stream | K880G6 | |

Table 7-3. Key Component Solution Information

| Key Component | | | |
|-------------------------|--------------------------------|------------------------|--|
| Company | Description | Part Number | Remark |
| Acer Synergy Tech Corp | System integration Provider | | |
| DOW | DOWSIL | Experimental candidate | Long term required for Safety & Life Cycle |
| PERSTORP | POE | Experimental candidate | Long term required for Safety & Life Cycle |
| Chevron | PAO | Control candidate | |
| Mandala | 4U10kW WAIC | A19I04W10D0100A | |
| | 12U15kW WAIC | A19I12W15D0100A | |
| | 48U60kW WAIC | A19I48U60D0100A | |
| | 2U3kW AAIC | A19I02W03D0100A | |
| | 4U7kW AAIC | A19I007D0100A | |
| Switch Providers | | | To be updated |
| Mandala | Convex-louver heat sink module | A13HE01A0209Z | |
| Mandala | Convex-louver fin | A13HEA1A0100Z | |
| Optical Cable Providers | | | To be updated |

Call to Action

Let's work together to



- Develop liquid cooling solutions for optimum power usage, lower PUE, and better TCO
- Build partner solutions to accelerate ecosystem readiness

The Intel logo is centered on a solid blue background. It features the word "intel" in a white, lowercase, sans-serif font. A small blue square is positioned above the first vertical stroke of the letter 'i'. To the right of the word "intel" is a small white registered trademark symbol (®).

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